

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	375	257/725.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/08/01 08:07
L8	35235	sip "system-in-package" "system-in-a- package" (system near2 package)	US-PGPUB; USPAT	OR	ON	2008/08/01 08:16
L9	83	L8 same (capacit\$6 near coupl\$6)	US-PGPUB; USPAT	OR	ON	2008/08/01 08:16
L10	151	L8 and ((capacit\$6 near coupl\$6) same (guard\$6 ring\$6 ground\$6))	US-PGPUB; USPAT	OR	ON	2008/08/01 08:23
L11	8863	257/723.ccls. 257/725. ccls. 257/777.ccls. 257/786.ccls. 257/ E23.02.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/08/01 08:33
L12	467	L11 and (sip "system-in- package" "system-in-a- package" (system near2 package))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/01 08:33
L13	16	L12 and (capacit\$6 near coupl\$6)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/01 08:33
L14	57	L11 and ((capacit\$6 near coupl\$6) same (guard\$6 ring\$6 ground\$6))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/01 08:36
L15	11431	sip "system-in-package" "system-in-a- package" (system near2 package)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:40
L16	12	L15 and (capacit\$6 near coupl\$6)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:40
L17	4	L15 and ((guard\$6 ground\$6) with ring\$6)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:44
L18	3132	(capacit\$6 near coupl\$6) and (guard\$6 ring\$6 ground\$6)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:45

L19	1123	L18 and (semiconductor wafer substrate integrated ic chip die dice)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:45
L20	64	L19 and (package encapsulated)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/01 08:45
L21	8353	((sip "system-in-package" "system-in-a-package" (system near2 package) transmit receive signal) and (capacitance near2 (coupled communication) and (guard ring ground)).clm.	US-PGPUB; USPAT	OR	ON	2008/08/01 08:55
L22	14	((sip "system-in-package" "system-in-a-package" (system near2 package)) and (transmit receive signal) and (capacitance near2 (coupled communication) and (guard ring ground)).clm.	US-PGPUB; USPAT	OR	ON	2008/08/01 08:56
L23	738	((sip "system-in-package" "system-in-a-package" (system near2 package) ((semiconductor device component chip die dice) near4 (first second two another other))) and (transmit receive signal) and (capacitance near2 (coupled communication) and (guard ring ground)).clm.	US-PGPUB	OR	ON	2008/08/01 08:59
L24	348	((sip "system-in-package" "system-in-a-package" (system near2 package) ((semiconductor device component chip die dice) near2 (first second two another other))) and (transmit receive signal) and (capacitance near2 (coupled communication) and (guard ring ground) and (pad electrode	US-PGPUB	OR	ON	2008/08/01 09:01

		terminal land\$6)).clm.				
L25	135	((sip "system-in-package" "system-in-a-package" (system near2 package) ((semiconductor device component chip die dice) near2 (first second two another other))) and (transmi\$8 receiv\$6 signal\$6) and (capacit\$6 near2 (coupl\$6 communicat\$6)) and (guard\$6 ring\$6 ground \$6) and (pad electrode terminal land\$6) and (dielectric insulat\$6 separat\$6 spac\$6 oxide dioxide nitride)).clm.	US-PGPUB	OR	ON	2008/08/01 09:03
L26	46	((sip "system-in-package" "system-in-a-package" (system near2 package) ((semiconductor device component chip die dice) near2 (first second two another other))) and ((transmi\$8 receiv\$6 signal\$6) with (capacit\$6 near2 (coupl\$6 communicat\$6))) and (guard\$6 ring\$6 ground \$6) and (pad electrode terminal land\$6) and (dielectric insulat\$6 separat\$6 spac\$6 oxide dioxide nitride)).clm.	US-PGPUB	OR	ON	2008/08/01 09:04

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